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PRE-APPEAL BRIEF REQUEST FOR REVIEW

Docket Number (Optional)

ITL.0998US (P16010)

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)]

Application Number

10/696,207

Filed

October 29, 2003

on July 11, 2008Signature Typed or printed
name

Nancy Meshkoff

First Named Inventor

Mark J. Gallina

Art Unit

1795

Examiner

Harry D. Wilkins, III

Applicant requests review of the final rejection in the above-identified application. No amendments are being filed with this request.

This request is being filed with a notice of appeal.

The review is requested for the reason(s) stated on the attached sheet(s).

Note: No more than five (5) pages may be provided.

I am the

☐ applicant/inventor.☐ assignee of record of the entire interest.

See 37 CFR 3.71. Statement under 37 CFR 3.73(b) is enclosed.
(Form PTO/SB/96)

☒ attorney or agent of record.Registration number 28,994☐ attorney or agent acting under 37 CFR 1.34.

Registration number if acting under 37 CFR 1.34 _____



Signature

Timothy N. Trop

Typed or printed name

(713) 468-8880

Telephone number

July 11, 2008

Date

NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below*.

☐ *Total of _____ forms are submitted.

This collection of information is required by 35 U.S.C. 132. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11, 1.14 and 41.6. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:	§	
Mark J. Gallina	§	Art Unit: 1795
	§	
Serial No.: 10/696,207	§	Examiner: Harry D. Wilkins III
	§	
Filed: October 29, 2003	§	Docket: ITL.0998US
	§	P16010
For: Distributing Forces for	§	
Electrodeposition	§	Assignee: Intel Corporation
	§	

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

STATEMENT IN SUPPORT OF PRE-APPEAL REQUEST FOR REVIEW

Sir:

The claim relates to two different sides of a wafer, including a first side that is to be electrodeposited and a second or opposite side that is to be protected from electrodeposition. Electrical contacts make contact to the first side.

The limitation that is missing in the cited reference to Brogden is a base to seal the second side of the wafer. In the cited reference, the first side is the lower side of the wafer 24, shown in Figure 4. It is the side on the underside of the page on which the figure is depicted. We know this because the contacts 36 contact the underside. Thus, the second side is the top of the wafer or the upper surface of the page on which Figure 3 is printed.

The question then becomes what protects that upper side from being electrodeposited? The office action suggests that it is the sealing ring 40. But this is not true. As clearly explained

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Nancy Meshkoff

in the specification, it is the lid 50 that protects the upper side of the wafer from electrodeposition:

Thus, a sealing connection is formed on one side of the wafer 24 to prevent exposure of the electroplating solution, while the lid 50 keeps the other side of the wafer unexposed to the electroplating solution.

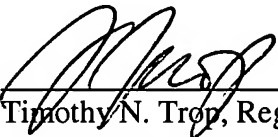
See column 3, lines 59-62. Obviously, then, the sealing ring 40 is insufficient to protect the second side, unlike the situation in the present application.

In the response to arguments, it was noted that "... the base in claim 1 directly contacts the first side of the wafer, to seal the second side of the wafer. Brogden exactly matches this structure." To the contrary, he does not. He needs the cover 50 to protect the second side because the asserted base 40 is ineffective for this purpose, as explicitly pointed out by Brogden.

Therefore, reconsideration would be appropriate.

Respectfully submitted,

Date: July 11, 2008



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